	Hits	Search Text	Time Stamp	DBs
9	0	(metallic adj pad and wafer and pick and place).clm.	2005/10/31 10:35	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT

	Hits	Search Text	Time Stamp	DBs
54	77	semiconductor and active same (pad or standoff or stand adj2 off) with tool	2005/10/28 22:25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
55	0	protect$4 with (semiconductor adj2 (laser or chip)) with ad	2005/10/28 22:27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
56	894	protect$4 with (semiconductor adj2 (laser or chip)) with pad	2005/10/28 22:27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
57	88	protect$4 with (semiconductor adj2 (laser or chip)) with pad same wafer	2005/10/28 22:27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
58	12	("4689797" | "4783788" | "4813050" | "4965525" | "5223170" | "5663974" | "5960020" | "5999673" | "6014396" | "6037189" | "6075801" | "6278720").PN.	2005/10/31 08:00	US-PGPUB; USPAT; USOCR

	Hits	Search Text	Time Stamp	DBs
1	6	("4728628" | "4830980" | "5208183" | "5474954" | "5504768" | "5658823").PN.	2005/10/31 08:06	US-PGPUB; USPAT; USOCR
2	11	("4689797" | "4728628" | "4783788" | "4813050" | "4965525" | "5078516" | "5652812" | "5703895" | "6014396" | "6037189" | "6075801").PN.	2005/10/31 08:07	US-PGPUB; USPAT; USOCR
3	8	("5228101" | "5353364" | "5412748" | "5621837" | "6021149" | "6058234" | "6108477" | "6343171").PN.	2005/10/31 08:08	US-PGPUB; USPAT; USOCR
4	1	("5901265").PN.	2005/10/31 09:49	US-PGPUB; USPAT; USOCR
5	109	pad with kerf and (dicing die singulat$4 divid$4 separat$4)	2005/10/31 09:51	US-PGPUB; USPAT; USOCR
6	6	protect$4 near3 pad same pick adj2 place	2005/10/31 09:53	US-PGPUB; USPAT; USOCR
7	10	protect$4 with pad same pick adj2 place	2005/10/31 09:53	US-PGPUB; USPAT; USOCR
8	4	117 not 116	2005/10/31 09:53	US-PGPUB; USPAT; USOCR